

# MA27P02

## Silicon epitaxial planar type

For high frequency switch

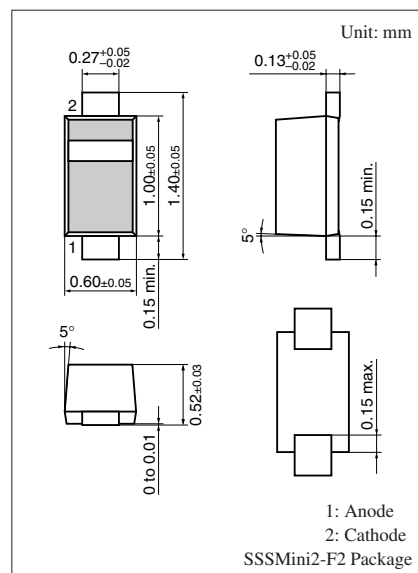
### ■ Features

- Small terminal capacitance  $C_t$
- Small forward dynamic resistance  $r_f$
- Ultraminiature package and surface mounting type  
1.0 mm × 0.6 mm (height: 0.52 mm)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter            | Symbol    | Rating      | Unit             |
|----------------------|-----------|-------------|------------------|
| Reverse voltage      | $V_R$     | 60          | V                |
| Forward current      | $I_F$     | 100         | mA               |
| Power dissipation *  | $P_D$     | 150         | mW               |
| Junction temperature | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature  | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

Note) \*: With a glass epoxy PC board



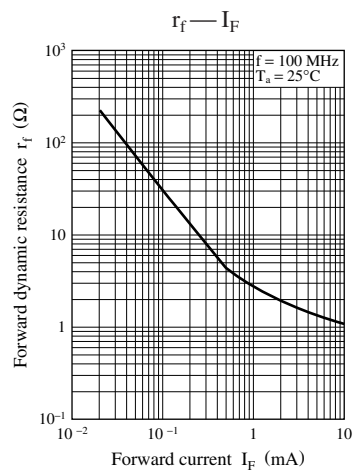
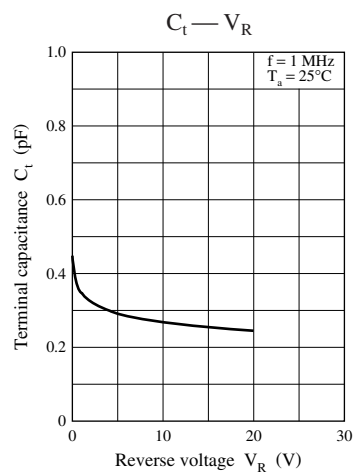
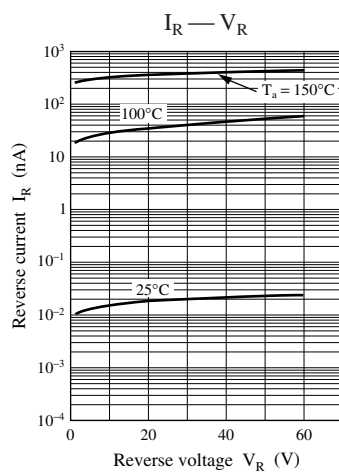
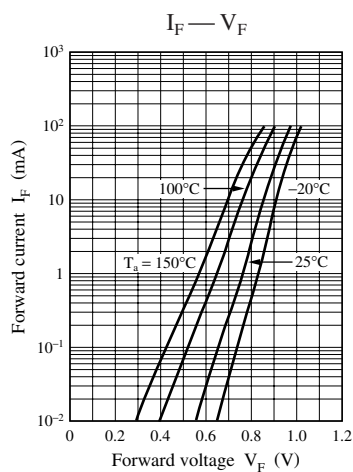
Marking Symbol: Y

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter                    | Symbol | Conditions                               | Min | Typ | Max | Unit     |
|------------------------------|--------|------------------------------------------|-----|-----|-----|----------|
| Forward voltage              | $V_F$  | $I_F = 10\text{ mA}$                     |     |     | 1.0 | V        |
| Reverse current              | $I_R$  | $V_R = 60\text{ V}$                      |     |     | 100 | nA       |
| Terminal capacitance         | $C_t$  | $V_R = 1\text{ V}, f = 1\text{ MHz}$     |     |     | 0.5 | pF       |
| Forward dynamic resistance * | $r_f$  | $I_F = 10\text{ mA}, f = 100\text{ MHz}$ |     |     | 2.0 | $\Omega$ |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. \*:  $r_f$  measurement device ; agilent model 4291B



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